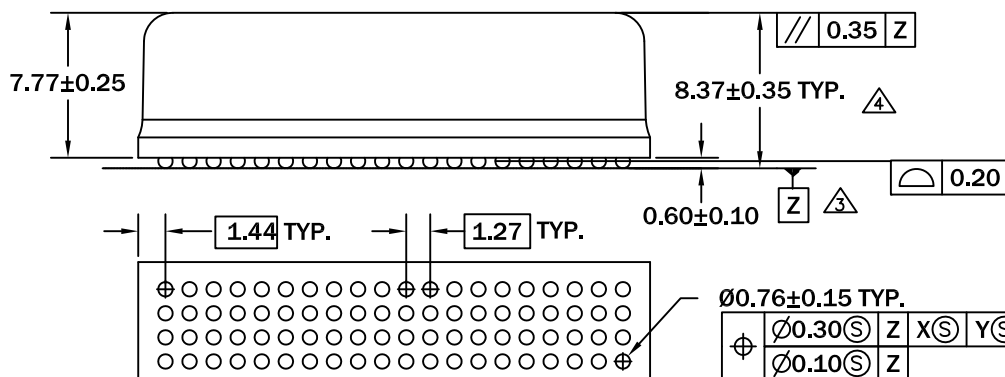
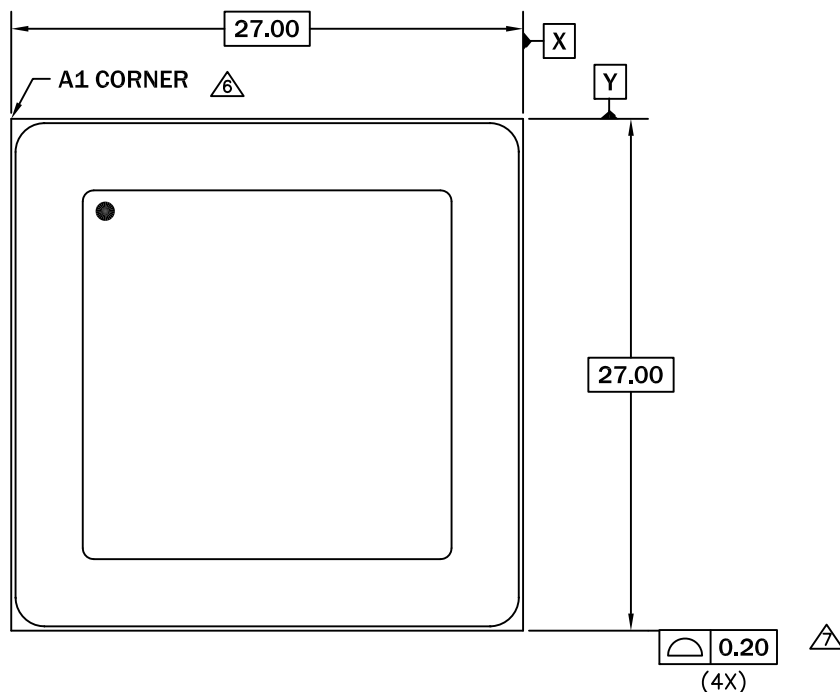


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A			



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- PRIMARY DATUM -Z- AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- THIS DIMENSION INCLUDES STAND-OFF HEIGHT AND PACKAGE BODY THICKNESS
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM -Z-.
- A1 CORNER MUST BE IDENTIFIED BY INK/LASER MARK ON TOP PACKAGE, AND METALLIZED MARKINGS ON BOTTOM PACKAGE
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- BASIC SOLDER BALL PITCH IS 1.27 MM

SIGNATURE

DATE

DOC. CONTROL:

ENGR. MGR:

MFG. ENGR:

CHECKED BY:

DRAWN BY:

TWM

JD

10/04

10/04

TITLE

MARKETING OUTLINE, 256 LEAD, PBGA (27X27)
1.27 MM PITCH, 8.20MM THICK, 2 LAYER

SIZE

FSCM NO.

PART NO.

REV.

A

21-0313

A

SCALE

N/A

SHEET

1 of 1

MAXIM